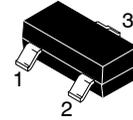# JFET Switching Transistors

N-Channel
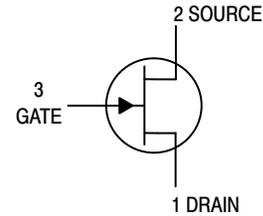
MMBF4391L, MMBF4392L, MMBF4393L

SOT−23
CASE 318
STYLE 10

Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

2 SOURCE
3 GATE
1 DRAIN

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain−Source Voltage	V_{DS}	30	Vdc
Drain−Gate Voltage	V_{DG}	30	Vdc
Gate−Source Voltage	V_{GS}	30	Vdc
Forward Gate Current	$I_{G(f)}$	50	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR−5 Board (Note 1) T_A = 25°C Derate above 25°C	P_D	225 1.8	mW mW/°C
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	556	°C/W
Junction and Storage Temperature Range	T_J, T_{stg}	−55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
1. FR−5 = 1.0 × 0.75 × 0.062 in.

MARKING DIAGRAM

XXX M ▪

1
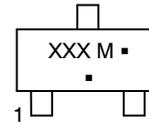
XXX = Specific Device Code
M   = Date Code*
▪   = Pb−Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

MARKING & ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 2 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Gate−Source Breakdown Voltage (I_G = 1.0 μAdc, V_{DS} = 0)	$V_{(BR)GSS}$	30	–	Vdc
Gate Reverse Current (V_{GS} = 15 Vdc, V_{DS} = 0, T_A = 25°C) (V_{GS} = 15 Vdc, V_{DS} = 0, T_A = 100°C)	I_{GSS}	 – –	 1.0 0.20	 nAdc μAdc
Gate−Source Cutoff Voltage (V_{DS} = 15 Vdc, I_D = 10 nAdc) 　MMBF4391LT1 　MMBF4392LT1 　MMBF4393LT1	$V_{GS(off)}$	 −4.0 −2.0 −0.5	 −10 −5.0 −3.0	Vdc
Off−State Drain Current (V_{DS} = 15 Vdc, V_{GS} = −12 Vdc) (V_{DS} = 15 Vdc, V_{GS} = −12 Vdc, T_A = 100°C)	$I_{D(off)}$	 – –	 1.0 1.0	 nAdc μAdc
ON CHARACTERISTICS				
Zero−Gate−Voltage Drain Current (V_{DS} = 15 Vdc, V_{GS} = 0) 　MMBF4391LT1 　MMBF4392LT1 　MMBF4393LT1	I_{DSS}	 50 25 5.0	 150 75 30	mAdc
Drain−Source On−Voltage (I_D = 12 mAdc, V_{GS} = 0) 　MMBF4391LT1 (I_D = 6.0 mAdc, V_{GS} = 0) 　MMBF4392LT1 (I_D = 3.0 mAdc, V_{GS} = 0) 　MMBF4393LT1	$V_{DS(on)}$	 – – –	 0.4 0.4 0.4	Vdc
Static Drain−Source On−Resistance (I_D = 1.0 mAdc, V_{GS} = 0) 　MMBF4391LT1 　MMBF4392LT1 　MMBF4393LT1	$r_{DS(on)}$	 – – –	 30 60 100	Ω
SMALL−SIGNAL CHARACTERISTICS				
Input Capacitance (V_{DS} = 0 Vdc, V_{GS} = −15 Vdc, f = 1.0 MHz)	C_{iss}	–	14	pF
Reverse Transfer Capacitance (V_{DS} = 0 Vdc, V_{GS} = −12 Vdc, f = 1.0 MHz)	C_{rss}	–	3.5	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

Device	Marking	Package	Shipping[†]
MMBF4391LT1G	6J	SOT−23 (Pb−Free)	3,000 / Tape & Reel
SMMBF4391LT1G*	6J		
MMBF4392LT1G	6K		
MMBF4393LT1G	M6G		
SMMBF4393LT1G*	M6G		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

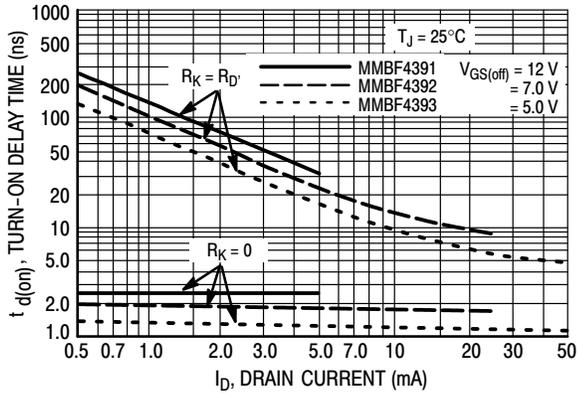# MMBF4391L, MMBF4392L, MMBF4393L

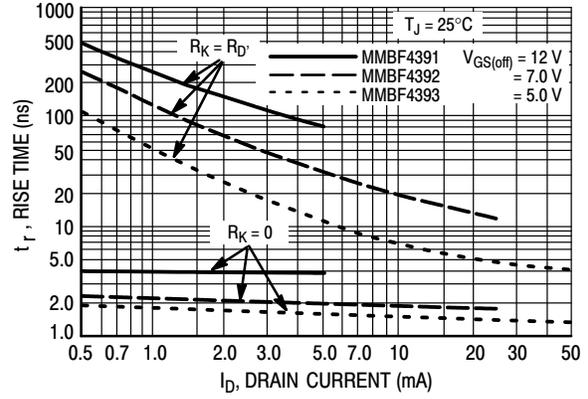## TYPICAL CHARACTERISTICS

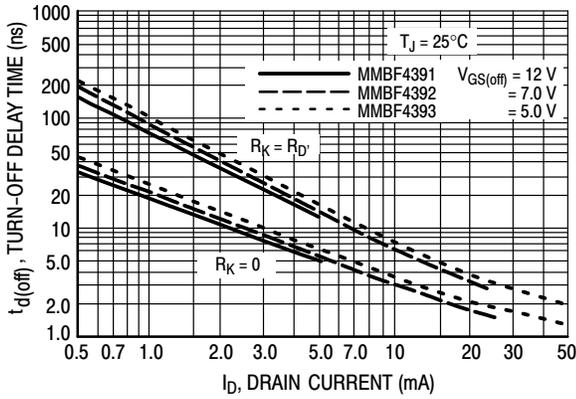Figure 1. Turn−On Delay Time

Figure 2. Rise Time

Figure 3. Turn−Off Delay Time

Figure 4. Fall Time

MMBF4391L, MMBF4392L, MMBF4393L
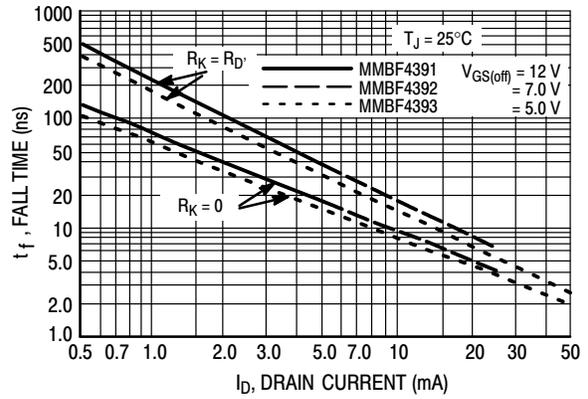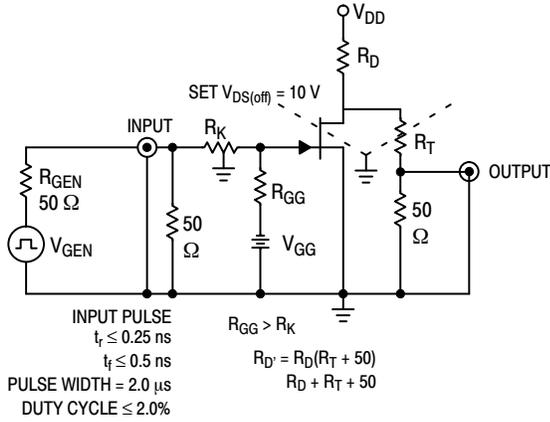
Figure 5. Switching Time Test Circuit

INPUT PULSE
$t_r \leq 0.25$ ns
$t_f \leq 0.5$ ns
PULSE WIDTH = 2.0 μs
DUTY CYCLE ≤ 2.0%

SET $V_{DS(off)}$ = 10 V

$R_{GG} > R_K$

$R_{D'} = \dfrac{R_D(R_T + 50)}{R_D + R_T + 50}$

NOTE 1

The switching characteristics shown above were measured using a test circuit similar to Figure 5. At the beginning of the switching interval, the gate voltage is at Gate Supply Voltage ($-V_{GG}$). The Drain–Source Voltage (V_{DS}) is slightly lower than Drain Supply Voltage (V_{DD}) due to the voltage divider. Thus Reverse Transfer Capacitance (C_{rss}) of Gate–Drain Capacitance (C_{gd}) is charged to $V_{GG} + V_{DS}$.

During the turn–on interval, Gate–Source Capacitance (C_{gs}) discharges through the series combination of R_{Gen} and R_K. C_{gd} must discharge to $V_{DS(on)}$ through R_G and R_K in series with the parallel combination of effective load impedance (R'_D) and Drain–Source Resistance (r_{DS}). During the turn–off, this charge flow is reversed.

Predicting turn–on time is somewhat difficult as the channel resistance r_{DS} is a function of the gate–source voltage. While C_{gs} discharges, V_{GS} approaches zero and r_{DS} decreases. Since C_{gd} discharges through r_{DS}, turn–on time is non–linear. During turn–off, the situation is reversed with r_{DS} increasing as C_{gd} charges.

The above switching curves show two impedance conditions; 1) R_K is equal to $R_{D'}$ which simulates the switching behavior of cascaded stages where the driving source impedance is normally the load impedance of the previous stage, and 2) R_K = 0 (low impedance) the driving source impedance is that of the generator.
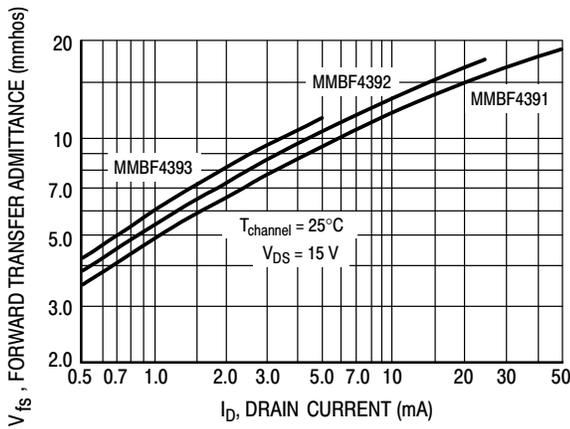
Figure 6. Typical Forward Transfer Admittance
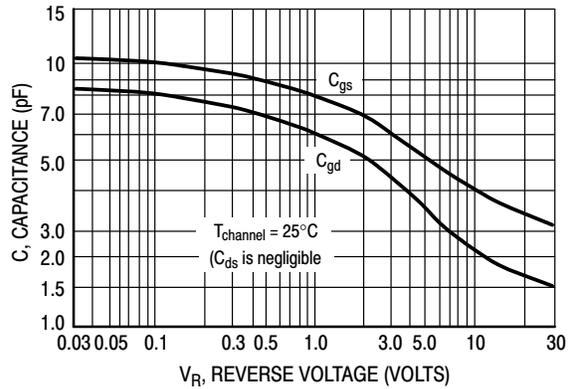
Figure 7. Typical Capacitance
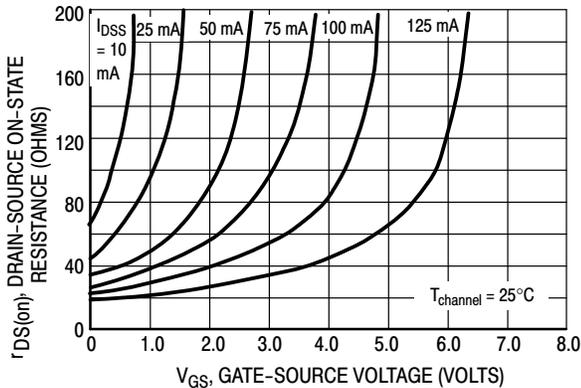
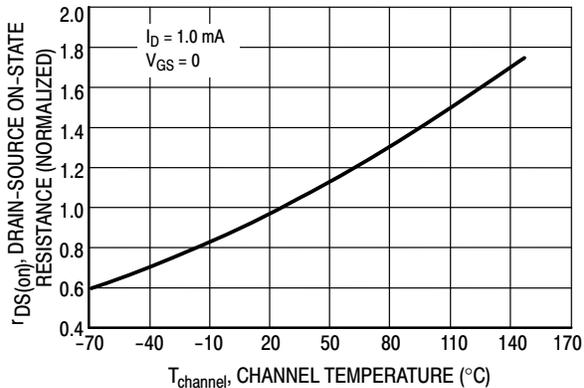**Figure 8. Effect of Gate–Source Voltage on Drain–Source Resistance**

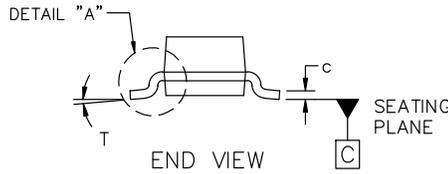**Figure 9. Effect of Temperature on Drain–Source On–State Resistance**

MMBF4391L, MMBF4392L, MMBF4393L

Figure 10. Effect of I$_{DSS}$ on Drain−Source Resistance and Gate−Source Voltage

NOTE 2

The Zero−Gate−Voltage Drain Current (I$_{DSS}$) is the principle determinant of other J−FET characteristics. Figure 10 shows the relationship of Gate−Source Off Voltage (V$_{GS(off)}$) and Drain−Source On Resistance (r$_{DS(on)}$) to I$_{DSS}$. Most of the devices will be within ±10% of the values shown in Figure 10. This data will be useful in predicting the characteristic variations for a given part number.

For example:

Unknown

r$_{DS(on)}$ and V$_{GS}$ range for an MMBF4392

The electrical characteristics table indicates that an MMBF4392 has an I$_{DSS}$ range of 25 to 75 mA. Figure 10 shows r$_{DS(on)}$ = 52 Ω for I$_{DSS}$ = 25 mA and 30 Ω for I$_{DSS}$ = 75 mA. The corresponding V$_{GS}$ values are 2.2 V and 4.8 V.

SOT−23 (TO−236) 2.90x1.30x1.00 1.90P
CASE 318
ISSUE AU

DATE 14 AUG 2024

SCALE 4:1

TOP VIEW

DETAIL "A"
Scale 3:1

0.25

L

L1

SIDE VIEW

A

A1

DETAIL "A"

END VIEW

SEATING PLANE

c

T

C

3X b

e

D

B

A

E

H_E

3

1   2
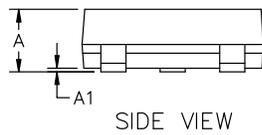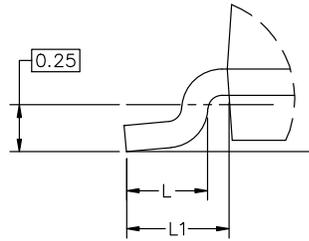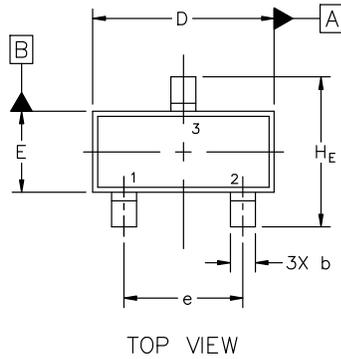
MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.89	1.00	1.11
A1	0.01	0.06	0.10
b	0.37	0.44	0.50
c	0.08	0.14	0.20
D	2.80	2.90	3.04
E	1.20	1.30	1.40
e	1.78	1.90	2.04
L	0.30	0.43	0.55
L1	0.35	0.54	0.69
H$_E$	2.10	2.40	2.64
T	0°	−−−	10°

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

GENERIC MARKING DIAGRAM*

XXXM▪

1

XXX = Specific Device Code
M   = Date Code
▪   = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

2.90

3X 0.95

3X 0.56

0.95

PITCH

RECOMMENDED MOUNTING FOOTPRINT
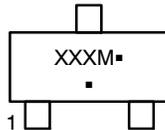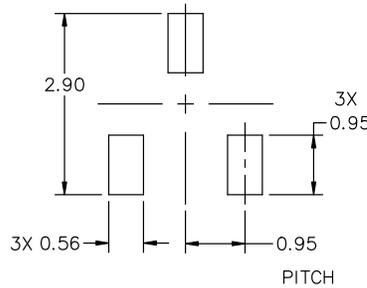
* For additional information on our Pb−Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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DESCRIPTION:	SOT−23 (TO−236) 2.90x1.30x1.00 1.90P		PAGE 1 OF 2

STYLE 1 THRU 5:
CANCELLED

STYLE 6:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

STYLE 7:
PIN 1. EMITTER
2. BASE
3. COLLECTOR

STYLE 8:
PIN 1. ANODE
2. NO CONNECTION
3. CATHODE

STYLE 9:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 10:
PIN 1. DRAIN
2. SOURCE
3. GATE

STYLE 11:
PIN 1. ANODE
2. CATHODE
3. CATHODE–ANODE

STYLE 12:
PIN 1. CATHODE
2. CATHODE
3. ANODE

STYLE 13:
PIN 1. SOURCE
2. DRAIN
3. GATE

STYLE 14:
PIN 1. CATHODE
2. GATE
3. ANODE

STYLE 15:
PIN 1. GATE
2. CATHODE
3. ANODE

STYLE 16:
PIN 1. ANODE
2. CATHODE
3. CATHODE

STYLE 17:
PIN 1. NO CONNECTION
2. ANODE
3. CATHODE

STYLE 18:
PIN 1. NO CONNECTION
2. CATHODE
3. ANODE

STYLE 19:
PIN 1. CATHODE
2. ANODE
3. CATHODE–ANODE

STYLE 20:
PIN 1. CATHODE
2. ANODE
3. GATE

STYLE 21:
PIN 1. GATE
2. SOURCE
3. DRAIN

STYLE 22:
PIN 1. RETURN
2. OUTPUT
3. INPUT

STYLE 23:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 24:
PIN 1. GATE
2. DRAIN
3. SOURCE

STYLE 25:
PIN 1. ANODE
2. CATHODE
3. GATE

STYLE 26:
PIN 1. CATHODE
2. ANODE
3. NO CONNECTION

STYLE 27:
PIN 1. CATHODE
2. CATHODE
3. CATHODE

STYLE 28:
PIN 1. ANODE
2. ANODE
3. ANODE

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ADDITIONAL INFORMATION

◊